

SC111002P
patent application

1. (amended) A method of manufacturing a semiconductor component comprising:

providing a substrate with a surface;

providing a layer comprised of undoped gallium arsenide over the surface of the substrate;

forming a gate contact over a first portion of the layer; and

removing a second portion of the layer to expose a portion of the surface of the substrate, wherein the remaining first portion of said layer does not substantially extend beyond the horizontal profile of said gate contact.

16. (amended) A method of manufacturing a semiconductor component comprising:

providing a delta-doped, heteroepitaxial semiconductor substrate with a surface, the delta-doped, heteroepitaxial semiconductor substrate comprising:

a support layer comprised of semi-insulating gallium arsenide;

a buffer layer comprised of undoped gallium arsenide overlying the support layer;

a doping layer delta-doped with silicon and overlying the buffer layer;

a spacer layer comprised of undoped gallium arsenide and overlying the doping layer;

a channel layer comprised of indium gallium arsenide and overlying the spacer layer; and

a barrier layer comprised of aluminum gallium arsenide and overlying the channel layer, the barrier layer forming the surface for the delta-doped, heteroepitaxial semiconductor substrate;

providing an undoped gallium arsenide capping layer having a thickness of approximately three to twelve nanometers and

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overlying the surface of the delta-doped, heteroepitaxial semiconductor substrate;

forming a gate contact over the undoped gallium arsenide capping layer, the gate contact covering a first portion of the undoped gallium arsenide capping layer and absent over a second portion of the undoped gallium arsenide capping layer;

removing the second portion of the undoped gallium arsenide capping layer after forming the gate contact to expose a portion of the surface of the delta-doped, heteroepitaxial semiconductor substrate, wherein the remaining first portion of said undoped gallium arsenide capping layer does not substantially extend beyond the horizontal profile of said gate contact;

forming a spacer adjacent to the gate contact;

forming source and drain regions in the delta-doped, heteroepitaxial semiconductor substrate; and

forming source and drain contacts over the source and drain regions after removing the second portion of the undoped gallium arsenide capping layer.

In accordance with 37 CFR § 1.121(c)(1)(ii), please find attached to this Response a separate marked-up copy of the immediately preceding rewritten claims. The attached page is captioned "**VERSION WITH MARKINGS TO SHOW CHANGES MADE**".

REMARKS

In the November 30, 2001 Office Action, claims 1-25 are acknowledged as pending in the Application, wherein the Examiner has rejected claims 1-21 and removed claims 22-25 from consideration. After entry of the instant amendment, claims 1-21 are pending. Support for the amendment of claims 1 and 16 may be found at page 5, lines 15-16 of the specification. No new matter has therefore been introduced.